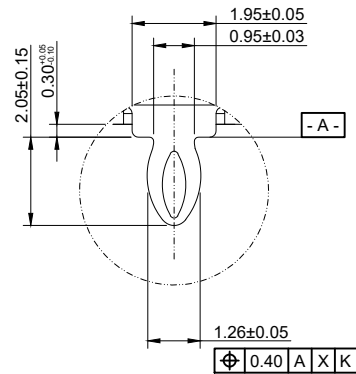
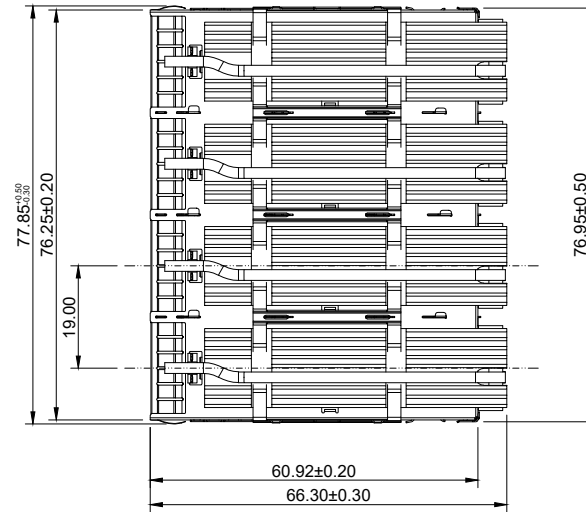




Detail B

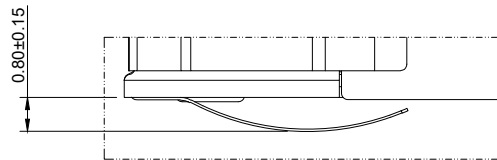
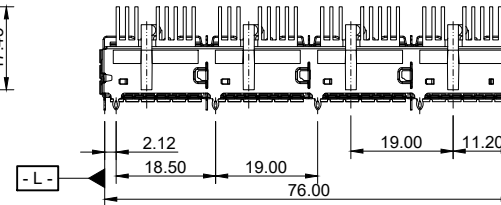
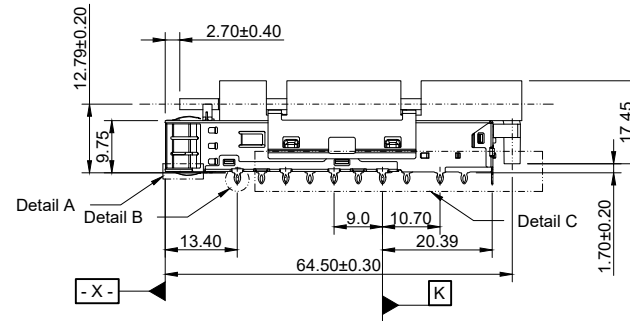
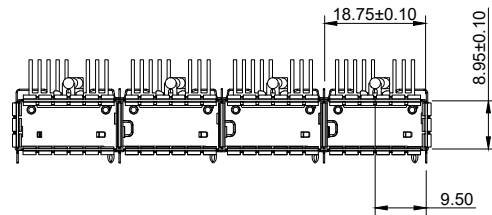


NOTE

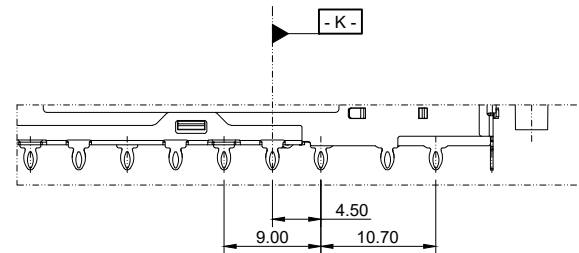
MATERIAL

CAGE : COPPER ALLOY, 30~80u" Ni PLATING
EMI SPRING : BERYLLIUM COPPER, 1.27~2.032um Ni PLATING
HEAT SINK : ALUMINUM
HEAT SINK CLIP : STEEL
LIGHT PIPE : POLYCARBONATE TRANSPARENT

1. SEE QSFP MSF SPECIFICATION FOR BEZEL LOCATION TOLERANCE
2. DATUM A IS TIP SURFACE OF HOST BOARD PEA MSA
3. FINISHED HOLE SIZE (AFTER PLATING)
4. DATUM K IS HOST BOARD THREE HOLE #1 TO ACCEPT CONNECTOR GUIDE POST PER MSA
5. DATUM L IS HOST BOARD THREE HOLE #2 TO ACCEPT CONNECTOR GUIDE POST PER MSA
6. DATUM T IS HARS STOP ON CAGE PER MSA

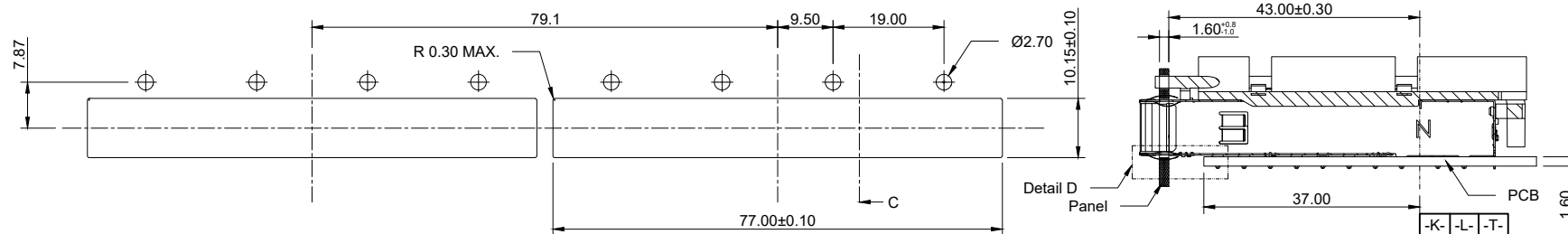


Detail A

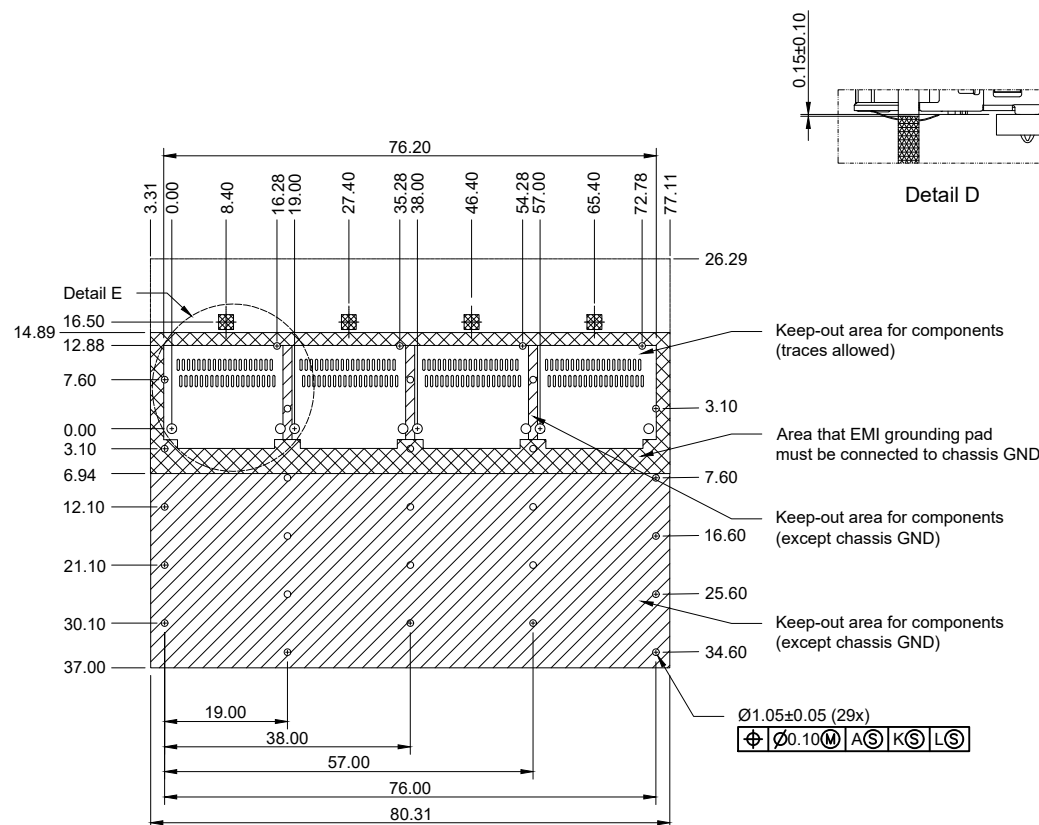


Detail C

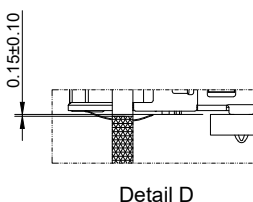
			UNIT	mm
			REVISION	X1
PRODUCT			TOLERANCES	
QSF28 1x4 CAGE			X±0.25 XX±0.13 XXX±0.10 ANGLES±2°	
DWG NO.		PART NO.		
EZQS10-4PH2-02				
PROJECTION	SCALE	SHEET	1 OF 3	



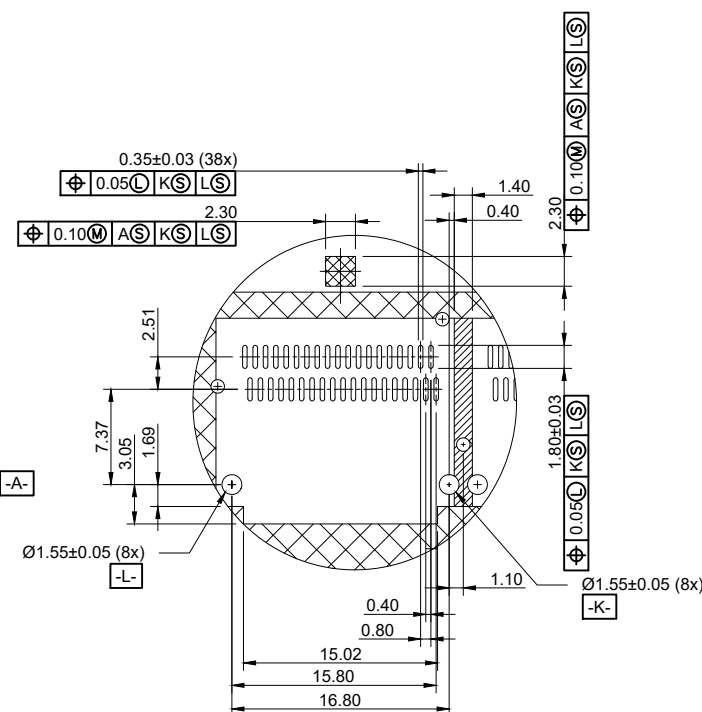
RECOMMENDED PANEL OPENING FOR SINGLE SIDE



RECOMMENDED PCB LAYOUT

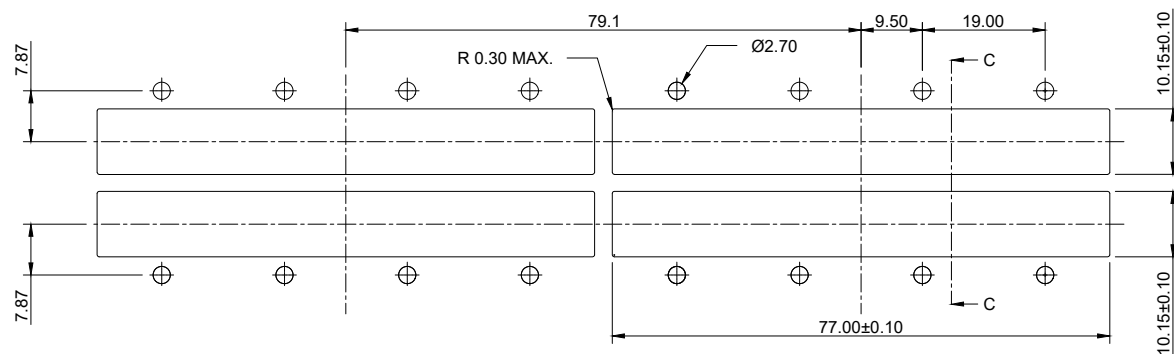


Detail D

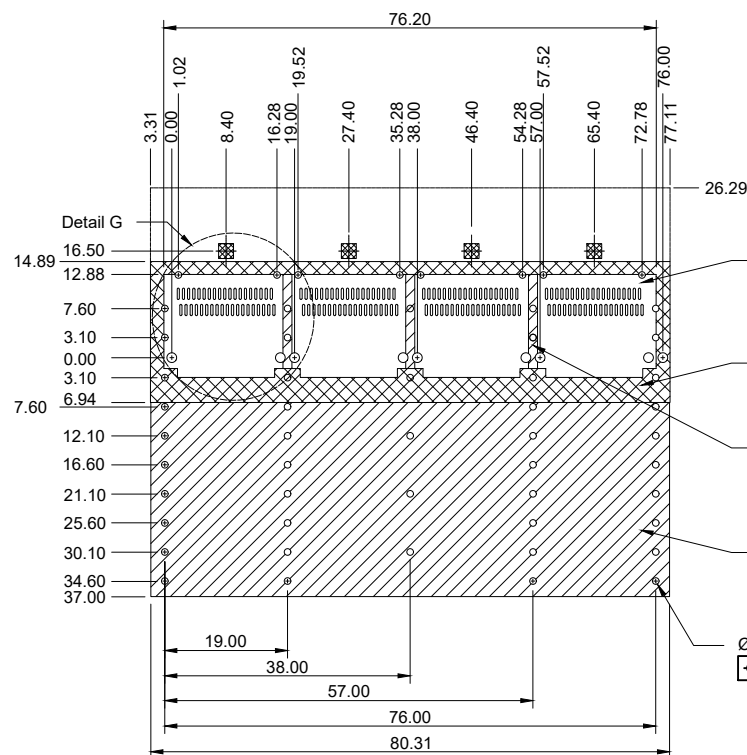
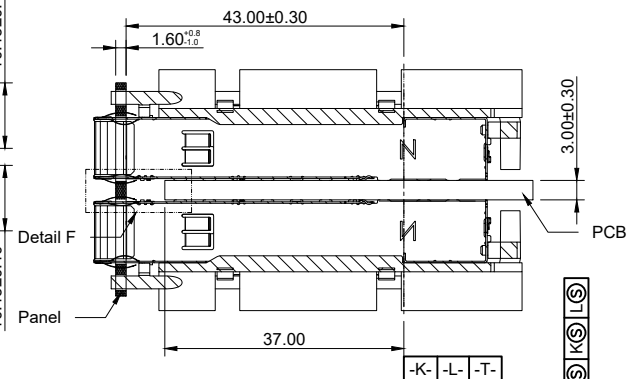


Detail E

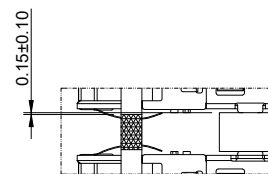
		UNIT	mm
		REVISION	X1
PRODUCT		TOLERANCES	
QSF28 1x4 CAGE		X±0.25 XX±0.13 XXX±0.10 ANGLES±2°	
DWG NO.	PART NO.		
EZQS10-4PH2-02			
PROJECTION	SCALE	SHEET	2 OF 3



RECOMMENDED PANEL OPENING FOR DOUBLE SIDES



RECOMMENDED PCB LAYOUT



Detail F

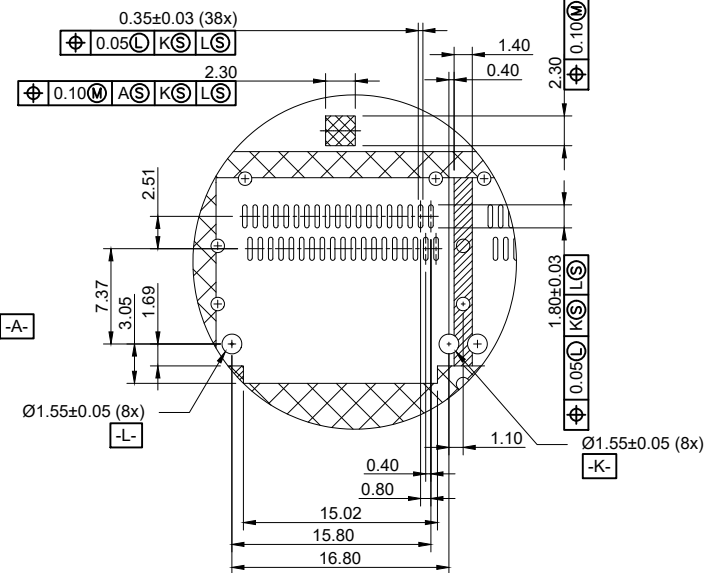
Keep-out area for components (traces allowed)

Area that EMI grounding pad must be connected to chassis GND

Keep-out area for components (except chassis GND)

Keep-out area for components (except chassis GND)

Ø1.05±0.05 (53x)
Ø0.10(M) A(S) K(S) L(S)



Detail G

		UNIT	mm
		REVISION	X1
PRODUCT		TOLERANCES	
QSF28 1x4 CAGE		X±0.25 XX±0.13 XXX±0.10 ANGLES±2°	
DWG NO.	PART NO.		
EZQS10-4PH2-02			
PROJECTION	SCALE	SHEET	3 OF 3